

IN THE CLAIMS:

Please add new claims 8-11 as follows:

LISTING OF CURRENT CLAIMS

Claim 1. (Original) An IC package with an implanted heat-dissipation fin, comprising:

an encapsulant having a PCB side and an opposing open side;

a chip inside the encapsulant; and

a heat-dissipation fin implanted in the encapsulant and having a portion thereof extending outside the open side.

Claim 2. (Original) The IC package with an implanted heat-dissipation fin according to claim 1, wherein said heat-dissipation fin contacts directly with said chip.

Claim 3. (Original) The IC package with an implanted heat-dissipation fin according to claim 1, wherein said heat-dissipation fin spaces from said chip by a predetermined spacing.

Claim 4. (Original) The IC package with an implanted heat-dissipation fin according to claim 1, wherein said portion of said heat-dissipation fin further has at least a hookup point.

Claim 5. (Original) A method for implanting a heat-dissipation fin while packing an IC chip, comprising:

having a chip encapsulated inside an encapsulant at a melted state;

before the encapsulant being cured, implanting a heat-dissipation fin into the encapsulant at a predetermined position above the chip and with a portion of the heat-dissipation fin left outside the encapsulant; and

holding in position the encapsulant and the heat-dissipation fin till the encapsulant being cured.

Claim 6. (Original) The method for implanting a heat-dissipation fin while packing an IC chip according to claim 5, wherein said predetermined position is a solid contact state.

Claim 7. (Original) The method for implanting a heat-dissipation fin while packing an IC chip according to claim 5, wherein said predetermined position is a position with a predetermined spacing.

Claim 8. (New) The IC package with an implanted heat-dissipation fin according to claim 1, wherein said heat-dissipation fin comprises a bottom portion having at least one opening for said encapsulant filling within the opening of the bottom portion.

Claim 9. (New) The IC package with an implanted heat-dissipation fin according to claim 8, wherein said heat-dissipation fin further comprises a plurality of upper portion contacting said bottom portion and extending to outsides of said open side.

Claim 10. (New) The method for implanting a heat-dissipation fin while packing an IC chip according to claim 5, wherein said heat-dissipation fin comprises a bottom portion having at least one opening for said encapsulant filling within the opening of the bottom portion.

Claim 11. (New) The method for implanting a heat-dissipation fin while packing an IC chip according to claim 10, wherein said heat-dissipation fin further comprises a plurality of upper portion contacting said bottom portion and extending to outsides of said open side.